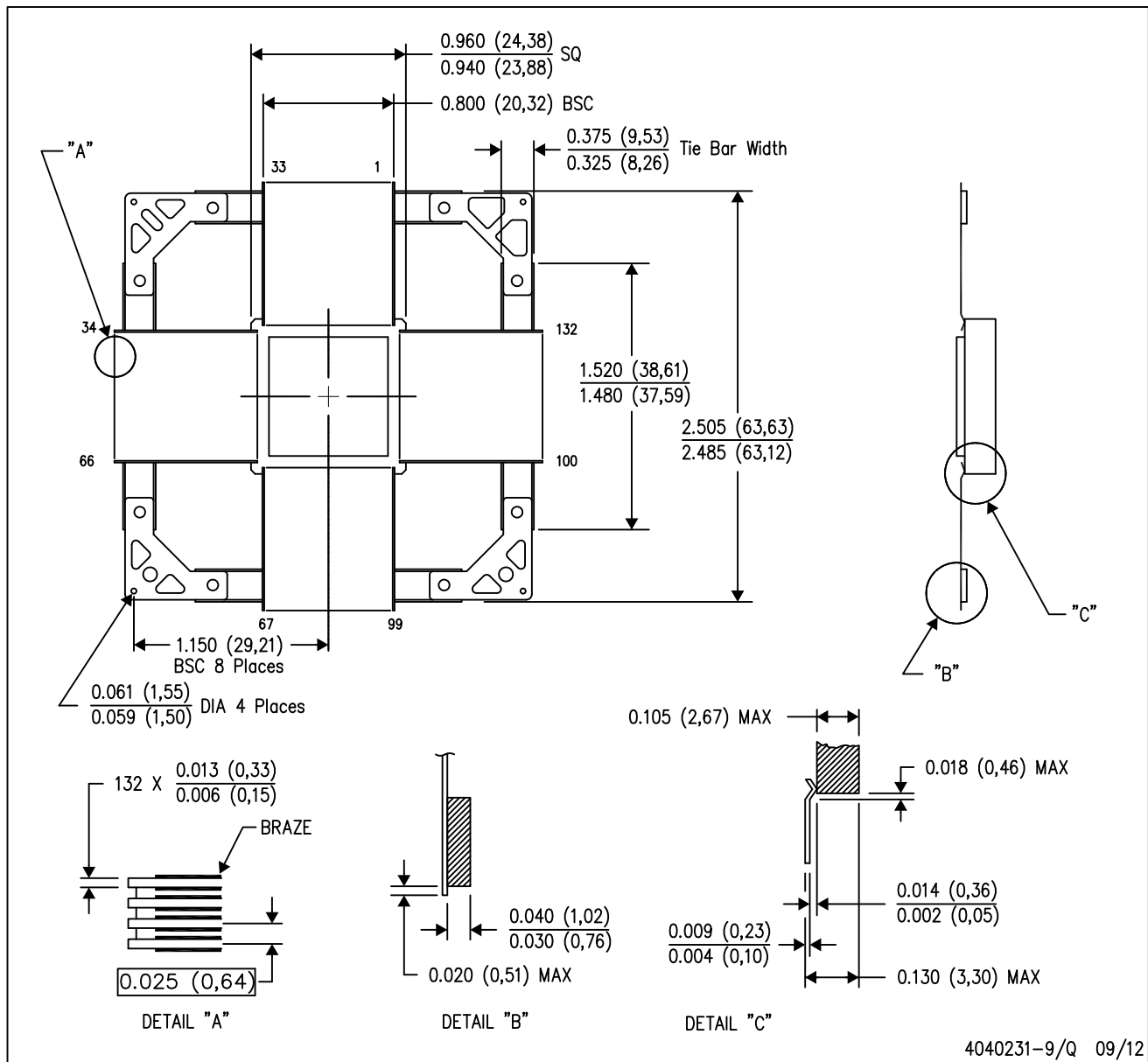


HFG (S-CQFP-F132)

CERAMIC QUAD FLATPACK WITH NCTB



4040231-9/Q 09/12

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
 - This package is hermetically sealed with a metal lid.
 - The leads are gold plated and can be solderdipped.
 - Leads not shown for clarity purposes.
 - Falls within JEDEC MO-113AC

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